

- Approved new Graduate Fellowship of \$10K with \$5K travel support to begin in 2008; modeled after the Motorola/IEEE CPMT Graduate Fellowship.
- Approved Johan Liu as a CPMT Distinguished Lecturer.
- Approved George Harman as a CPMT Distinguished Lecturer.
- Approved appointment of Eric Beyne as Strategic Director, Region 8.

Reports were presented as follows:

- CPMT President's Vision for CPMT Society
- Finances
- Publications
- Transactions
- Conferences
- Region 10 Activities
- ECTC Integration/57th ECTC
- Education
- Nominations
- Fellows Evaluation
- Fellows Search
- Constitution and Bylaws
- Technical Programs
- Region 8 Programs
- Membership and Chapters
- Student Programs
- Awards and Recognition
- Marketing

The next meeting of the CPMT Board of Governors is scheduled for 9-10 November 2007 following the ECTC Paper Selection Meeting, Dallas, TX, USA.

The meeting was adjourned at 4:30 pm.

Board of Governors Workshop Summary

Submitted by Dr. Dave Palmer, IEEE Fellow, Sandia National Laboratories

CPMT President William Chen held the third workshop for the Society Board of Governors on Friday, 1st June 2007, evening in Reno right after the ECTC. A few "new" members were introduced: Petri Savolainen, Kitty Pearsall, Paul Franzon, Eric Beyne, and Philip Chan.

The President quickly reviewed the results of the first workshop where each of the thrusts of our Society (publications, conferences, technical committees, education programs, chapter and membership development, and awards and recognition) were reviewed with the "value proposition" perspective to see how to enhance the impact for our members and our profession.

The second workshop addressed the Society's efforts at Globalization to serve the more geographically dispersed members. A few potential chapter areas (high member density) have been chosen to concentrate our effort: Ottawa, Austin, Germany, Norway, Japan, Malaysia, and Korea.

Much discussion was on the attempt not to let the good work of various parts of the Society to be limited within their own Silo (stovepipe). For example, the great organization of ECTC does feed into Chapter development, publications

(best papers are fed into the Transactions input), technical committee growth (TCs meet at breakfast meetings), and awards (given at luncheons). However not all of our activities are this synergistic.

Several topics were discussed in some detail including publications enhancements such as shortening time to print and eliminating laggard manuscripts. Linking publications to specific conferences and expanding our stakeholders by adding authors, editors, and reviewers for the Transactions were examples of using publications as a catalyst for the Society.

Dimitry Grabbe Presented IEEE Technical Field Award for Components, Packaging and Manufacturing Technology

Submitted by Ms. Jacquelyn Hampton, Potomac Communications Group

- *Dimitry Grabbe awarded IEEE Technical Field Award for Components Packaging and Manufacturing Technology - Award is one of the highest honors conferred by the IEEE*
- *Grabbe's contributions have played an integral part in advancing U.S. space exploration*

PISCATAWAY, N.J., June 14, 2007 - Dimitry Grabbe was presented the IEEE Technical Field Award for Components, Packaging and Manufacturing Technology on May 31 during the 57th Electronic Components and Technology Conference in Reno, Nev. USA.



Grabbe was recognized for his contributions to the fields of electrical/electronic connector technology and development of multi-layer wiring boards. The award is part of the Technical Field Awards program and is sponsored by the IEEE Components, Packaging and Manufacturing Technology Society. It recognizes commendable contributions to the advancement

of components, electronic packaging or manufacturing technologies.

"There are very few engineers who have made as many contributions to advancing electronic and optoelectronic connectors and associated technologies," said Grabbe's peer who nominated him for the award. "For the last fifty years, Dimitry has been a leader in creating new products and new manufacturing approaches that have accounted for many significant improvements."

Dr. William T. Chen, President of the IEEE CPMT Society noted, "Mr. Grabbe is a brilliant individual whose efforts in electrical/electronic connector technology and the development of multi-layer wiring boards has contributed to major advancements in this industry."

Grabbe currently assists in research on gyroscopes and accelerometers with Dr. Pryputniewicz, professor of mechanical engineering and founding director of the Center for Holographic Studies and laser micro-mechanics at Worcester Polytechnic Institute in Mass.

Highlights from Grabbe's career:

- Pioneered work that has produced nearly 500 U.S. and foreign patents covering machine design, semiconductor packaging, electronics assembly and optoelectronic conductor design.

- His work in printed circuit board technology for electronic packaging led to the development of large, multi-layer printed circuit boards. This was crucial in helping U.S. astronauts gain greater real-time control of their space exploration activities.
- Founded the Maine Research Corporation which specialized in high-end printed circuit boards in 1964.
- Worked for AMP, Inc. and facilitated the organizations leadership in electrical/electronic connector technology, test socket technology and miniature semiconductor packages starting.
- Received the Leonard da Vinci Award from the American Society of Mechanical Engineers.
- Recognized by AMP (now part of Tyco Electronics) with a Lifetime Achievement Award.
- Named an IEEE Life Fellow.

Past recipients of the IEEE Technical Field Award for Components, Packaging and Manufacturing Technology:

2006 - C. P. Wong, Regent's Professor at Georgia Institute of Technology, Atlanta, Ga. For contributions in advanced polymeric materials science and processes for highly reliable electronic packages.

2005 - Yutaka Tsukada, Managing Director/General Manager of Advanced Packaging Technology Development, Kyocera SLC Technologies Corporation, Shiga-Ken, Japan. For pioneering contributions in micro-via technology for printed circuit boards, and for extending the feasibility of the direct flip-chip attachment process.

2004 - John W. Balde, Senior Consultant, Interconnection Decision Consulting, Flemington, N.J. For lifetime contributions to tantalum film technology and the introduction of new electronic packaging technology to development and manufacturing.

About the IEEE Technical Field Award for Components, Packaging and Manufacturing Technology

The award was first presented in 2004 and may be presented to an individual or a small team involved in device and systems packaging, including packaging of microelectronics, optoelectronics, RF and wireless and micro-electro-mechanical systems (MEMS).

Nominations are encouraged for next year's CPMT Field-Award; contact Len Schaper for details: schaper@uark.edu

**IEEE CPMT Society Honors 2007
Award Winners**

Submitted by Ms. Jacquelyn Hampton, Potomac Communications Group

- Awards presented during the 57th Electronic Components Technology Conference (ECTC) in Reno, Nevada, USA
- Georgia Institute of Technology faculty members receive two of six awards.
- Winners represent the depth and diversity of CPMT's global community of professionals

Piscataway, N.J., June 11, 2007 - The IEEE Components, Packaging and Manufacturing Technology Society (CPMT) recognized its 2007 award winners at the 57th Electronic Components and Technology Conference (ECTC) in Reno, Nevada, USA on May 31, 2007. William T. Chen, CPMT

Society president, presented the awards during the annual awards luncheon in front of an audience of more than 800 conference attendees. The Society gives these awards for distinguished performance in technical fields and dedication to the Society and profession.

"It is with great honor that I am able to present these awards to such fine recipients," said William T. Chen, President, CPMT Society. "Their exceptional contributions to the fields of components, packaging and manufacturing technology should be celebrated by all in this profession."

"It is these achievements that allow our industry to grow and thrive."

- **Rao R. Tummala** (Georgia Institute of Technology, USA) – *IEEE CPMT David Feldman Outstanding Contribution Award* – for the breadth of his contributions to the CPMT Society in numerous leadership roles, as well as their global impact; including his unprecedented two terms (four years) as CPMT Society President. This award is presented to recognize outstanding contributions to the fields encompassed by the CPMT Society through executive or managerial directions.



Tummala served as the CPMT Society President from 2000 - 2003. In this role he was responsible for revolutionizing the Society and identifying a number of critical and strategic needs. During his time in office he was able to expand the society by assisting in the formation of several Student Chapters and the creation of a number of CPMT Society Chapters throughout the world.

In addition to his work for the CPMT Society, Tummala is a successful industrial technologist and academician. He was named an IBM Fellow and served as the Director of the NSF Centers in Packaging. He has received many industry and academic awards including one of the Stars in U.S. for industry competitiveness and multiple awards from IEEE, IMAPS, I-ASM., SME, DVM and AM, Ceramic Society. He was named as a Distinguished Alumni from the University of Illinois and the Indian Institute of Science in Bangalore. He also received the highest faculty award from the Georgia Institute of Technology, the Class of 1934 Distinguished Professor Award.

- **Philip Garrou, Ph.D.**, (Cary, North Carolina) – *IEEE CPMT Outstanding Sustained Technical Contribution Award* – for 25 years of technical contributions and leadership in thin film dielectric materials and microelectric applications including multichip modules, bumping and wafer level packaging, integrated passives, oLEDs, and most recently 3D IC integration. This award is presented to an individual who has demonstrated outstanding sustained and continuing contributions to the technology fields encompassed by the CPMT Society.



As well as his more than two decades of service to the CPMT Society, Dr. Philip Garrou, is a global technical expert in thin film dielectric, or BCB. In the late 1980s there were several polymer dielectrics being used by several U.S. and Asian companies that were attempting to compete with the incumbent polyimide materials. Under Dr. Garrou's leadership,